



Semiconductor Device Type: CAX SOIC-8-0.150in-SnPb						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	0.00	(mg) Total	Die	% of Total Weight	0.00
Silicon	7440-21-3	Die	0.00	0.00	14		Silicon	7440-21-3	100.00	
Copper	7440-50-8	Leadframe	26.24	18.96	262420		Total 100.00			
Iron	7439-89-6	Leadframe	0.65	0.47	6506					
Lead	7439-92-1	Leadframe	0.00	0.00	14	20.00	(mg) Total	Leadframe	% of Total Weight	27.69
Phosphorus	7723-14-0	Leadframe	0.02	0.02	228		Copper	7440-50-8	94.79	
Zinc	7440-66-6	Leadframe	0.08	0.06	761		Iron	7439-89-6	2.35	
Silver	7440-22-4	Leadframe	0.69	0.50	6921		Lead	7439-92-1	0.01	
Silver	7440-22-4	Epoxy	5.82	4.20	58180		Phosphorus	7723-14-0	0.08	
exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	Epoxy	0.34	0.25	3426		Zinc	7440-66-6	0.28	
Epoxy resinProprietary	Trade Secret	Epoxy	0.03	0.02	343		Silver	7440-22-4	2.50	
Bis(alpha...alpha.-Dimethylbenzyl) peroxide	80-43-3	Epoxy	0.03	0.02	343		Total 100.00			
Gold	7440-57-5	Bonding Wire	0.42	0.30	4153					
Calcuim	7440-70-2	Bonding Wire	0.00	0.00	0	4.50	(mg) Total	Epoxy	% of Total Weight	6.23
Silica Fused	60676-86-0	Mold Compound	45.08	32.57	450797		Silver	7440-22-4	93.40	
Epoxy Resin	Trade Secret	Mold Compound	3.16	2.28	31561		exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	5.50	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.05	0.76	10520		Epoxy resinProprietary	Trade Secret	0.55	
Phenol Resin	Trade Secret	Mold Compound	3.16	2.28	31561		Bis(alpha...alpha.-Dimethylbenzyl) peroxide	80-43-3	0.55	
Carbon Black	1333-86-4	Mold Compound	0.16	0.11	1578		Total 100.00			
Tin	7440-31-5	Lead Finish Plating	11.11	8.02	111073					
Lead	7439-92-1	Lead Finish Plating	1.96	1.42	19601	0.30	(mg) Total	Bonding Wire	% of Total Weight	0.42
TOTALS: 72.24 mg Total Mass			100.00	72.24	1,000,000		Gold	7440-57-5	100.00	
							Calcuim	7440-70-2	0.00	
							Total 100.00			

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38.00	(mg) Total	Mold Compound	% of Total Weight	52.60
	Silica Fused	60676-86-0	85.70	
	Epoxy Resin	Trade Secret	6.00	
	Epoxy, Cresol Novolac	29690-82-2	2.00	
	Phenol Resin	Trade Secret	6.00	
	Carbon Black	1333-86-4	0.30	
	Total 100.00			
9.44	(mg) Total	Lead Finish Plating	% of Total Weight	13.07
	Tin	7440-31-5	85.00	
	Lead	7439-92-1	15.00	
	Total 100.00			

72.24

100.00